Panasonic
CONNECT

The NPM-W2 combines accurate component placement, precise SPI and AOI inspection and reproductive adhesive dispensing in one high-speed solution.

NPM-W2

Higher productivity and quality thanks to the integration of printing, placement and inspection processes make the NPM-W2 one of the most flexible and versatile pick-and-place solutions on the market.

Key Features

- Equipped with a 12-nozzle head and can place 38,500 components
- Automatical inspection of solder depots and components according to the production data
- HDF discharge mechanism compatible, which ensures high-quality non-contact dispensing with a screw valve-dispenser

NPM-W2

https://latam.connect.panasonic.com/co/pt/produtos/smart-factory-solutions/npm-w2

PCB dimensions (mm)	Single-laneBatch mounting2-positin mountingDual-laneDual transfer (Batch)Dual transfer (2-position)Single transfer (Batch)Single transfer (2-position
Placement Head max Speed	38 500cph (0.094 s/ chip)
Placement Head Placement Accuracy (Cpk≧1)	±40 µm / chip
Placement Head Component Dimensions (mm)	0402 chip ~ L 6 x W 6 x T 3
Dispensing Head	Dispensing speed:Dot dispensing: 0.16 s/dot (Condition : XY=10 mm, Z=less than 4 mm movement, No θ rotation) Draw dispensing: 4.25 s/component (Condition : 30 mm x 30 mm corner dispensing)*9Adhesive position accuracy (Cpk≥1) Dot Dispensing: ± 75 µ m /dot Draw Dispensing: ± 100 µ m /componentApplicable components Dot Dispensing: 1608 chip to SOP,PLCC,QFP, Connector, BGA, CSP Draw Dispensing: BGA, CSP
Resolution	2D inspection head (A)18 µm
View Size (mm)	44.4 x 37.2
Inspection Processing Time	Solder Inspection 0.35s/ View sizeComponent Inspection 0.5s/ View size
Inspection Object	Solder InspectionChip component: 100 µm × 150 µm or more (0603 or more)Package component: ϕ150 µm or moreComponent Inspection: Square chip (0603 or more), SOP, QFP (a pitch of 0.4mm or more), CSP, BGA, Aluminum electrolysis capacitor, Volume, Trimmer, Coil, Connector
Inspection Items	Solder Inspection:Oozing, blur, misalignment, abnormal shape, bridgingComponent Inspection:Missing, shift, flipping, polarity, foreign object inspection
Inspection Position Accuracy	± 20 µm
No of Inspection	Solder Inspection : Max. 30 000 pcs./machine (No. of components :Max. 10 000 pcs./machine)Component Inspection: Max. 10 000 pcs./machine
Component Supply Taping	Tape : 4 / 8 / 12 / 16 / 24 / 32 / 44 / 56 mmMax.120 (Tape: 4, 8 mm)